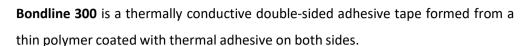
Bondline 300

Thermal Adhesive Tape





Bondline 300 is designed to attach two surfaces that require a strong, permanent bond, excellent thermal connection and guaranteed electrical insulation up to 65000 volts. **Bondline 300** offers a high performance thermal solution for bonding heat generating electronics to a heatsink, cold wall or chassis.

Features

- Double-sided, thermal adhesive tape consisting of a KAPTON polyimide film and silicone rubber
- Delivers excellent electrical isolation in combination with good thermal connection
- Pressure sensitive application improving to maximum bond strength after 24 hours

Availability

- Available in standard thickness of 0.12mm
- Supplied on 30m rolls in varying widths
- Available kiss-cut on rolls and as die-cut custom shapes

Benefits

- Removal of micro air voids between mating surfaces reduces thermal resistance
- Extremely thin bond line of 0.12mm for improved thermal performance
- High dielectric strength for demanding electronic applications

Recommended Uses

- Bonding PCBs and FR4s to a heatsink
- To cool devices in power supplies or power converters
- High voltage breakdown applications

Typical Physical Properties

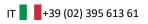
Property (unit)	Test Method	Bondline 300
Colour	Visual	Light Brown
Thermal Conductivity (W/mK)	ASTM D5470	0.40
Thickness (mm)	Visual	0.12
Thermal Resistance @ 10 PSI (°C in²/W)	ASTM D150	0.10
Operating Temp (°C)	In House	-20 to +150

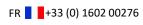
Mechanical and Electrical Properties

Property (unit)	Test Method	Bondline 300
Flammability	UL 94	НВ
Adhesion to Steel (N/cm)	ASTM 412	3.25
Breakdown Voltage (VAC)	ASTM D149	>6000
Shelf Life (months)	Visual	6



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This material is often used in these industries:







